# Onsemi

## **MOSFET** - Power, N-Channel, SUPERFET<sup>®</sup> III, Automotive, Easy-drive 650 V, 72 mΩ, 44 A NVHL072N65S3

#### Description

SuperFET III MOSFET is onsemi's brand-new high voltage super-junction (SJ) MOSFET family that is utilizing charge balance technology for outstanding low on-resistance and lower gate charge performance. This advanced technology is tailored to minimize conduction loss provide superior switching performance, and withstand extreme dv/dt rate. Consequently, SuperFET III MOSFET Easy-drive series helps manage EMI issues and allows for easier design implementation.

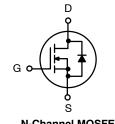
#### Features

- AEC-O101 Oualified
- Max Junction Temperature 150°C
- Typ.  $R_{DS}(on) = 61 \text{ m}\Omega$
- Ultra Low Gate Charge (Typ. Q<sub>G</sub> = 82 nC)
- Low Effective Output Capacitance (Typ. C<sub>OSS</sub>(eff.) = 724 pF)
- 100% Avalanche Tested
- These Devices are Pb-Free and are RoHS Compliant

#### **Typical Applications**

- Automotive PHEV-BEV DC-DC Converter
- Automotive Onboard Charger for PHEV-BEV

BV <sub>DSS</sub>	R <sub>DS(on)</sub> MAX	I <sub>D</sub> MAX
650 V	72 mΩ @ 10 V	44 A

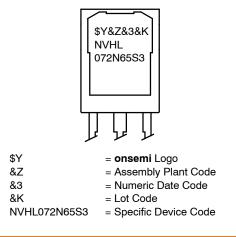


N-Channel MOSFET



TO-247-3LD CASE 340CX

#### MARKING DIAGRAM



#### **ORDERING INFORMATION**

See detailed ordering and shipping information on page 2 of this data sheet.

Symbol	Parameter		Value	Unit
V <sub>DSS</sub>	Drain to Source Voltage		650	V
V <sub>GSS</sub>	Gate to Source Voltage	DC	±30	V
		AC (f > 1 Hz)	±30	V
Ι <sub>D</sub>	Drain Current	Continuous (T <sub>C</sub> = 25°C)	44	Α
		Continuous (T <sub>C</sub> = 100°C)	28	Α
I <sub>DM</sub>	Pulsed Drain Current	Pulsed (Note 1)	110	Α
E <sub>AS</sub>	Single Pulsed Avalanche Energy (Note 2)		214	mJ
E <sub>AR</sub>	Repetitive Avalanche (Note 1)		3.12	mJ
dv/dt	MOSFET dv/dt		100	V/ns
	Peak Diode Recovery dv/dt (Note 3)		20	V/ns
PD	Power Dissipation	(T <sub>C</sub> = 25°C)	312	W
		Derate Above 25°C	2.5	W/°C
T <sub>J</sub> ,T <sub>STG</sub>	Operating and Storage Temperature Range		–55 to +150	°C
TL	Maximum Lead Temperature for Soldering, 1/8" from Case for 5 Seconds		300	°C

#### ABSOLUTE MAXIMUM RATINGS (T<sub>C</sub> = 25°C, Unless otherwise specified)

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected. 1. Repetitive rating: pulse-width limited by maximum junction temperature. 2.  $I_{AS} = 4.8 \text{ A}$ ,  $R_G = 25 \Omega$ , starting  $T_J = 25^{\circ}C$ . 3.  $I_{SD} < 44 \text{ A}$ , di/dt  $\leq 200 \text{ A/ms}$ , VDD  $\leq \text{BVDSS}$ , starting  $T_J = 25^{\circ}C$ . 4. Essentially independent of operating temperature typical characteristics.

#### **THERMAL CHARACTERISTICS**

Symbol	Parameter	Value	Unit
R <sub>θJ C</sub>	Thermal Resistance, Junction to Case, Max	0.37	°C/W
R <sub>θJ A</sub>	Thermal Resistance, Junction to Ambient, Max	40	°C/W

#### PACKAGE MARKING AND ORDERING INFORMATION

Part Number	Top Marking	Package	age Packing Method Shipping (Qty / Packing	
NVHL072N65S3	NVHL072N65S3	TO-247-3LD	Tube	30 Units / Tube

### **ELECTRICAL CHARACTERISTICS** (T<sub>C</sub> = $25^{\circ}$ C unless otherwise noted)

Q<sub>rr</sub>

Reverse Recovery Charge

Symbol	Parameter	Test Conditions	Min	Тур	Max	Unit
OFF CHARACT	ERISTICS	·				
BV <sub>DSS</sub> D	Drain-to-Source Breakdown Voltage	$V_{GS}$ = 0 V, $I_D$ = 1 mA, $T_J$ = 25°C	650	-	-	V
		$V_{GS} = 0 \text{ V}, \text{ I}_{D} = 1 \text{ mA}, \text{ T}_{J} = 150^{\circ}\text{C}$	700	-	-	V
$\Delta BVDSS / \Delta TJ$	Breakdown Voltage Temperature Coefficient	$I_D = 1$ mA, Referenced to 25°C	-	0.60	-	V/°C
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	$V_{DS} = 650 \text{ V}, \text{ V}_{GS} = 0 \text{ V}$	-	0.30	1	μA
		$V_{DS} = 520 \text{ V}, \text{ V}_{GS} = 0 \text{ V}, \text{ Tc} = 125^{\circ}\text{C}$	-	7.30	-	
I <sub>GSS</sub>	Gate to Body Leakage Current	$V_{GS} = \pm 30 \text{ V},  \text{V}_{DS} = 0 \text{ V}$	-	-	±100	nA
ON CHARACTE	RISTICS	·				
V <sub>GS(th)</sub>	Gate to Source Threshold Voltage	$V_{GS =} V_{DS}, I_{D} = 1.0 \text{ mA}$	2.5	-	4.5	V
R <sub>DS(on)</sub>	Static Drain to Source On Resistance	$V_{GS}$ = 10 V, I <sub>D</sub> = 22 A, T <sub>J</sub> = 25°C	-	61	72	mΩ
		$V_{GS}$ = 10 V, I <sub>D</sub> = 22 A, T <sub>J</sub> = 100°C	-	107	-	mΩ
9 <sub>FS</sub>	Forward Transconductance	V <sub>DS</sub> = 20 V, I <sub>D</sub> = 44 A	-	29.7	-	S
DYNAMIC CHAI	RACTERISTICS	•	•			
C <sub>iss</sub>	Input Capacitance	$V_{DS}$ = 400 V, $V_{GS}$ = 0 V, f = 1 MHz	-	3300	-	pF
C <sub>oss</sub>	Output Capacitance	1	-	72.8	-	pF
C <sub>rss</sub>	Reverse Transfer Capacitance	1	-	14.6	-	pF
C <sub>oss(eff.)</sub>	Effective Output Capacitance	$V_{DS}$ = 0 V to 400 V, $V_{GS}$ = 0 V	-	724	-	pF
C <sub>oss(er.)</sub>	Energy Related Output Capacitance	$V_{DS}$ = 0 V to 400 V, $V_{GS}$ = 0 V	-	104	-	pF
Q <sub>g(tot)</sub>	Total Gate Charge	$V_{DS} = 400 \text{ V}, \text{ V}_{GS} = 10 \text{ V}, \text{ I}_{D} = 44 \text{ A}$	-	82.0	-	nC
Q <sub>gs</sub>	Gate to Source Gate Charge	(Note 4)	-	23.3	-	nC
Q <sub>gd</sub>	Gate to Drain "Miller" Charge	1	-	34.0	-	nC
R <sub>G</sub>	Gate Resistance	f = 1 MHz	-	0.685	-	mΩ
SWITCHING CH	ARACTERISTICS	•	•			
t <sub>d(on)</sub>	Turn–On Delay Time	V <sub>DD</sub> = 400 V, I <sub>D</sub> = 44 A, V <sub>GS</sub> = 10 V,	-	26.3	-	ns
t <sub>r</sub>	Turn–On Rise Time	$R_{G} = 4.7 \Omega$ (Note 4)	_	50	-	ns
t <sub>d(off)</sub>	Turn–Off Delay Time		-	65.9	-	ns
t <sub>f</sub>	Fall Time		-	32	-	ns
DRAIN-SOURC	E DIODE CHARACTERISTICS		•	•		
۱ <sub>S</sub>	Maximum Continuous Drain to Source Diode Forward Current		-	-	44	Α
I <sub>SM</sub>	Maximum Plused Drain to Source Diode Forward Current		-	-	110	Α
V <sub>SD</sub>	Drain to Source Diode Forward Voltage	$V_{GS}$ = 0 V, $I_{SD}$ = 22 A	-	-	1.2	V
t <sub>rr</sub>	Reverse Recovery Time	$V_{GS}$ = 0 V, $I_{SD}$ = 44 A dI <sub>F</sub> /dt = 100 A/µs	-	576	-	nS
	•			I		L

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

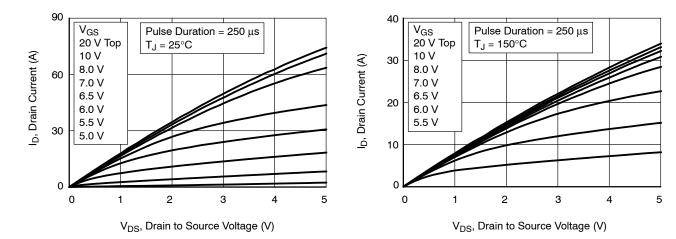
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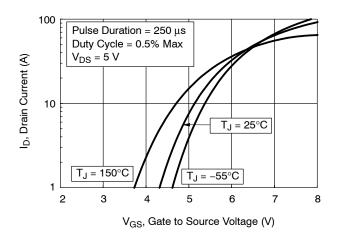
μC

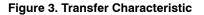
#### **TYPICAL CHARACTERISTICS**











I<sub>S</sub>, Reverse Drain Current (A)

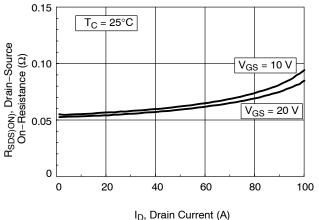


Figure 4. On-Resistance Variation vs. Drain Current and Gate Voltage

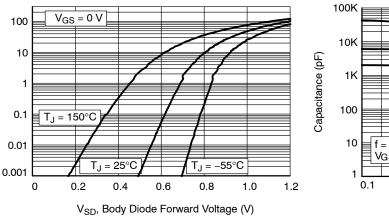
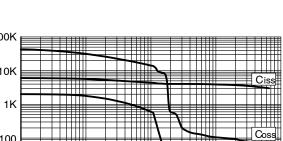


Figure 5. Forward Diode Characteristics



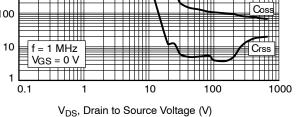


Figure 6. Capacitance vs. Drain to Source Volatage

#### TYPICAL CHARACTERISTICS (continued)

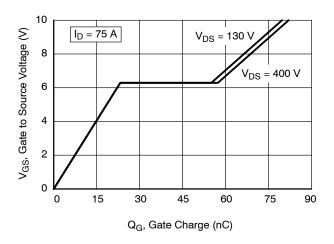


Figure 7. Gate Charge vs. Gate to Source Voltage

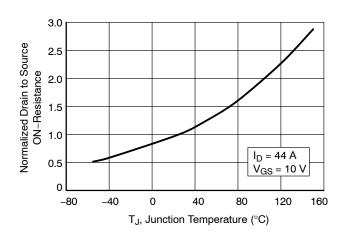


Figure 9. Normalized R<sub>DSON</sub> vs. Junction Temperature

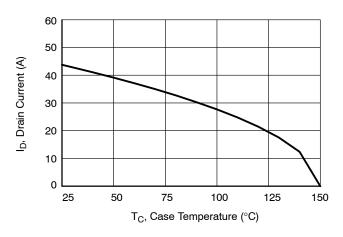


Figure 11. Maximum Continuous Drain Current vs. Case Temperature

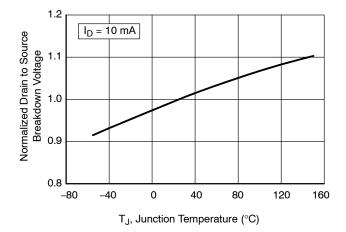


Figure 8. Normalized Drain to Source Breakdown Voltage vs. Junction Temperature

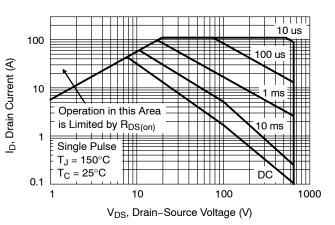
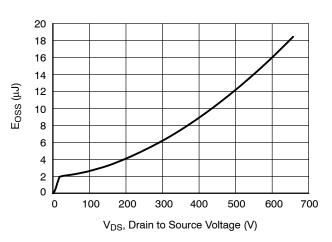
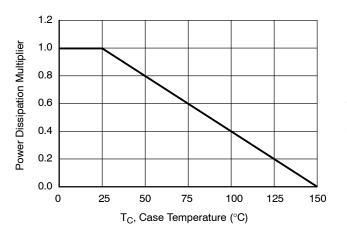


Figure 10. Forward Bias Safe Operating Area





#### TYPICAL CHARACTERISTICS (continued)





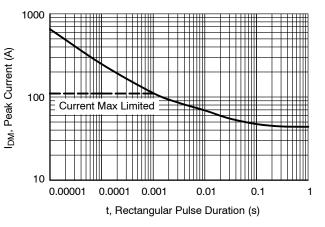


Figure 14. Peak Current Capability

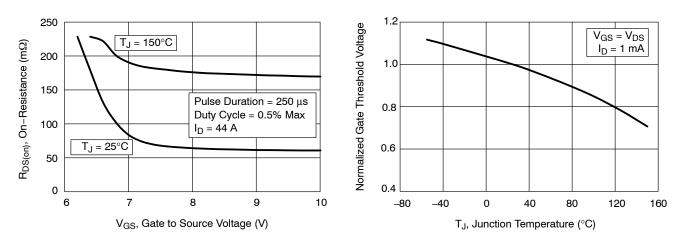
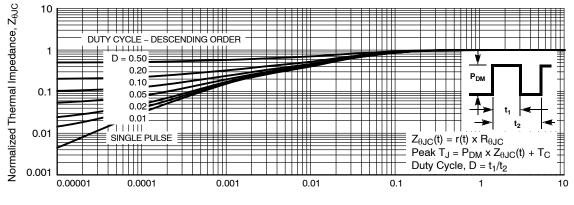


Figure 15. E<sub>OSS</sub> vs. Drain to Source Voltage

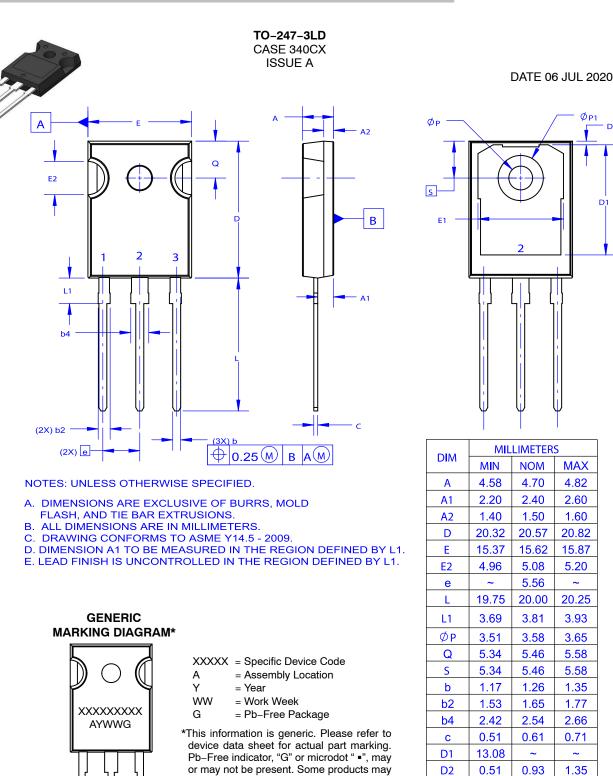
Figure 16. Normalized Gate Threshold Voltage vs. Temperature



t, Rectangular Pulse Duration (s)

Figure 17. Normalized Maximum Transient Thermal Impedance

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